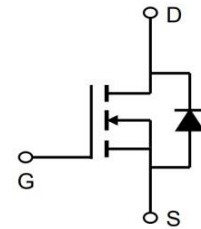


### Description

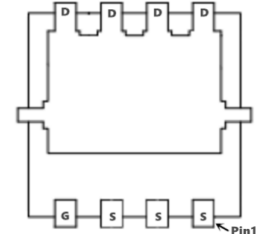
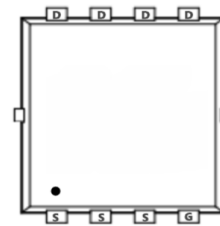
The LM5D80N10 uses advanced APM-SGT11 technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a Battery protection or in other Switching application.



### General Features

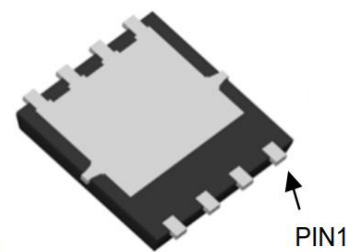
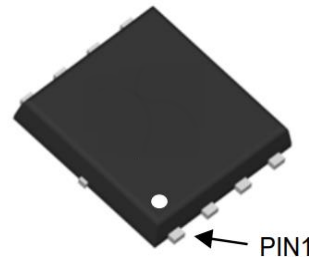
$V_{DS} = 100V$   $I_D = 80A$

$R_{DS(ON)} < 8m\Omega$  @  $V_{GS}=10V$  (Typ.6.5m $\Omega$ )



### Application

- DC/DC Converter
- LED Backlighting
- Power Management Switches



### Package Marking and Ordering Information

Device	Device Marking	Device Package	Reel Size	Tape width	Quantity
LM5D80N10	APG80N10NF	DFN5X6-8	-	-	5000 units

### Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_A = 25^\circ\text{C}$	Continuous Drain Current <sup>1</sup>	80	A
$I_D @ T_A = 70^\circ\text{C}$	Continuous Drain Current <sup>1</sup>	62	A
IDM	Pulsed Drain Current <sup>2</sup>	240	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	120	mJ
IAS	Avalanche Current	40	A
$P_D @ T_A = 25^\circ\text{C}$	Total Power Dissipation <sup>4</sup>	135	W
TSTG	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	62	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	0.84	$^\circ\text{C/W}$

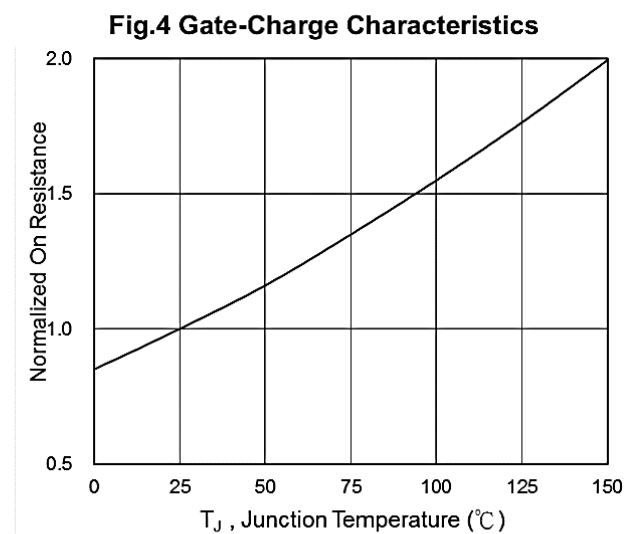
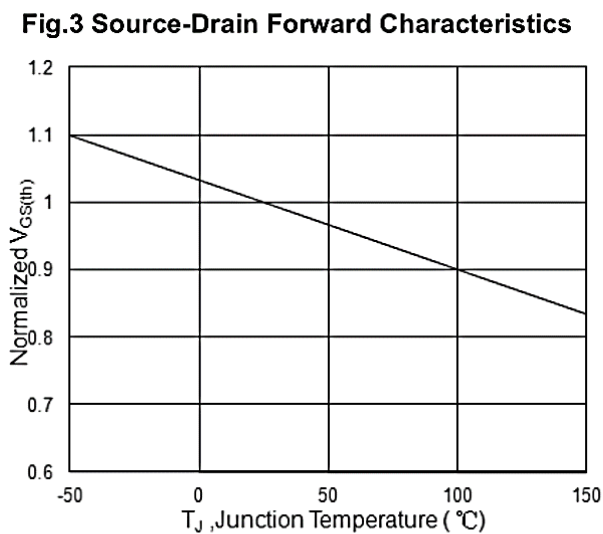
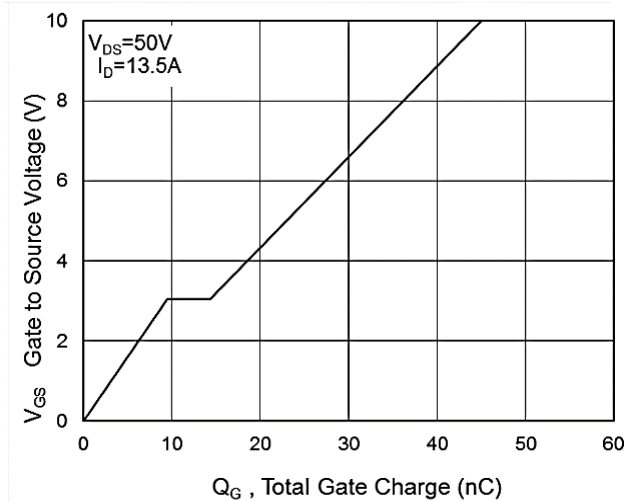
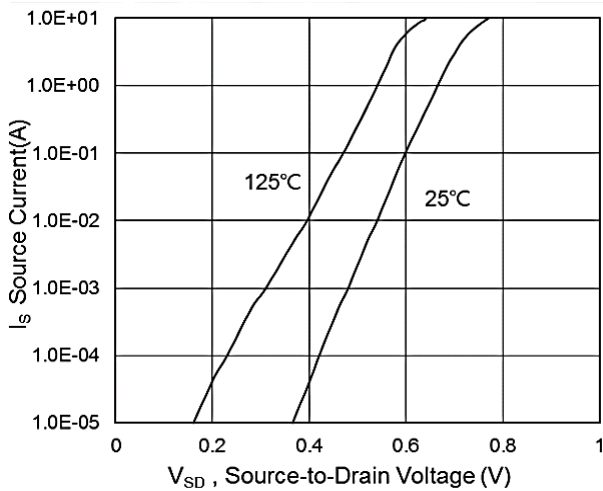
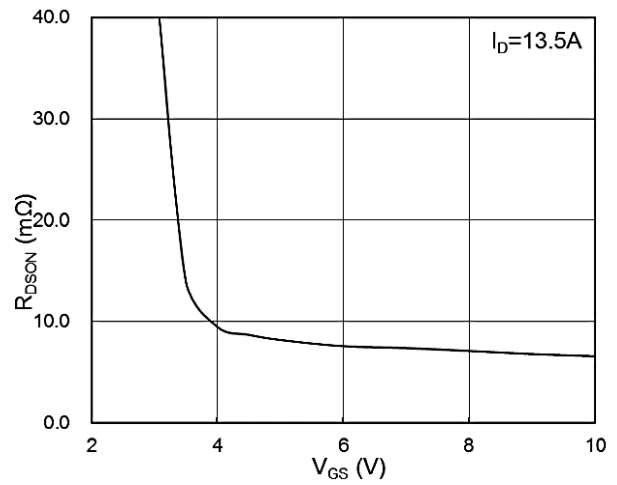
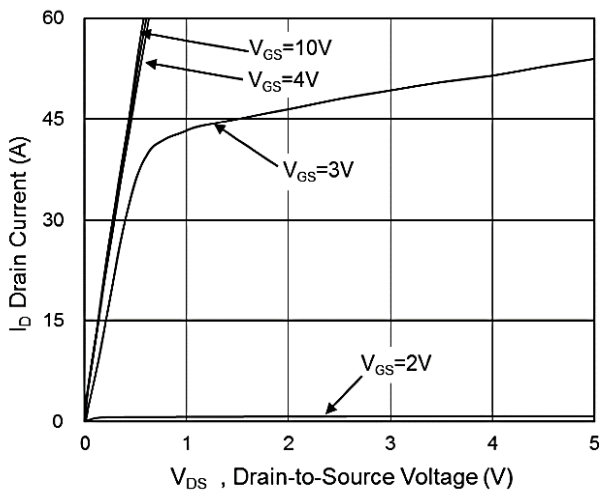
## Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	100	108	---	V
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =13.5A	---	6.5	8.0	mΩ
	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =11.5A	---	8.7	10.5	
VGS(th)	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	1.8	2.3	V
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C	---	---	5	
IGSS	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	---	---	±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =13.5A	---	75	---	S
Qg	Total Gate Charge (10V)	V <sub>DS</sub> =50V , V <sub>GS</sub> =10V , I <sub>D</sub> =13.5A	---	45	---	nC
Qg	Total Gate Charge (4.5V)		---	19.3	---	
Qgs	Gate-Source Charge		---	9.5	---	
Qgd	Gate-Drain Charge		---	4.8	---	
Td(on)	Turn-On Delay Time	V <sub>DD</sub> =50V , V <sub>GS</sub> =10V , R <sub>G</sub> =3Ω, I <sub>D</sub> =13.5A	---	10	---	ns
Tr	Rise Time		---	6.5	---	
Td(off)	Turn-Off Delay Time		---	45	---	
Tf	Fall Time		---	7.5	---	
Ciss	Input Capacitance	V <sub>DS</sub> =50V , V <sub>GS</sub> =0V , f=1MHz	---	3320	---	pF
Coss	Output Capacitance		---	605	---	
Crss	Reverse Transfer Capacitance		---	20	---	
IS	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	5	A
VSD	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C	---	---	1.1	V
trr	Reverse Recovery Time	I <sub>F</sub> =13.5A , di/dt=100A/μs , T <sub>J</sub> =25°C	---	33	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge		---	150	---	nC

### Note :

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、 The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=72V,V<sub>GS</sub>=10V, L=0.1mH I<sub>AS</sub>=40
- 4、 The power dissipation is limited by 150°C junction temperature
- 5、 The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation

## Typical Electrical and Thermal Characteristics



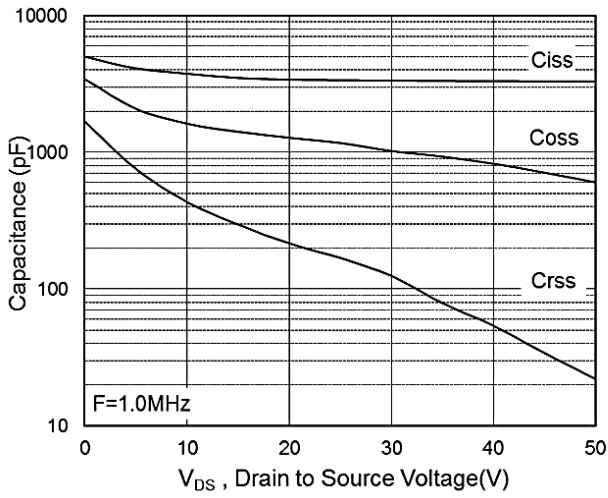


Fig.7 Capacitance

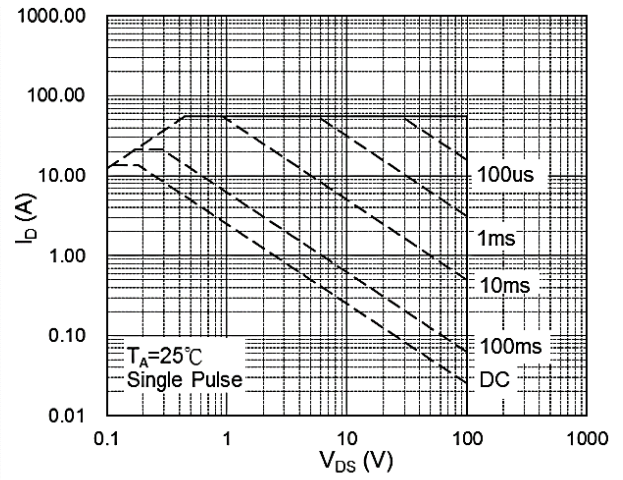


Fig.8 Safe Operating Area

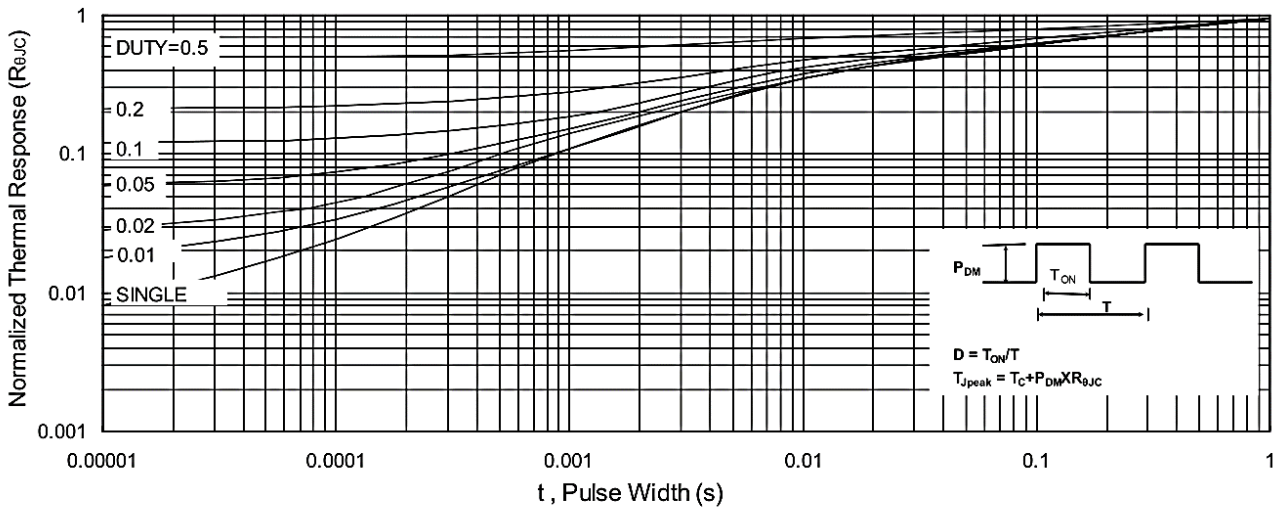


Fig.9 Normalized Maximum Transient Thermal Impedance

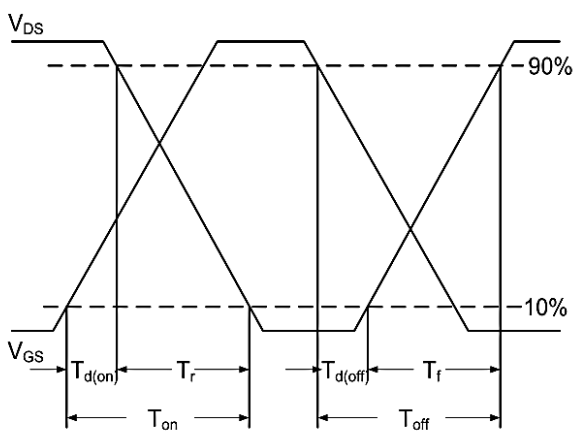


Fig.10 Switching Time Waveform

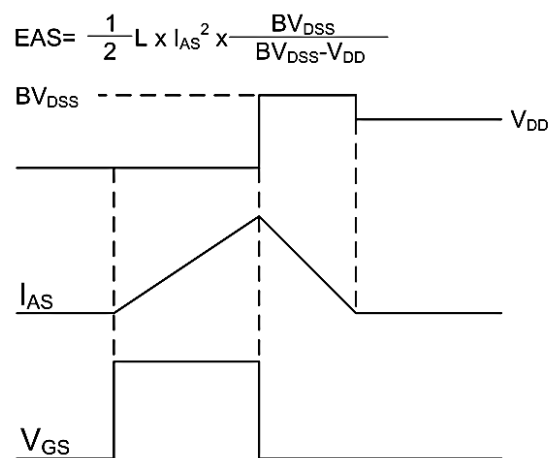
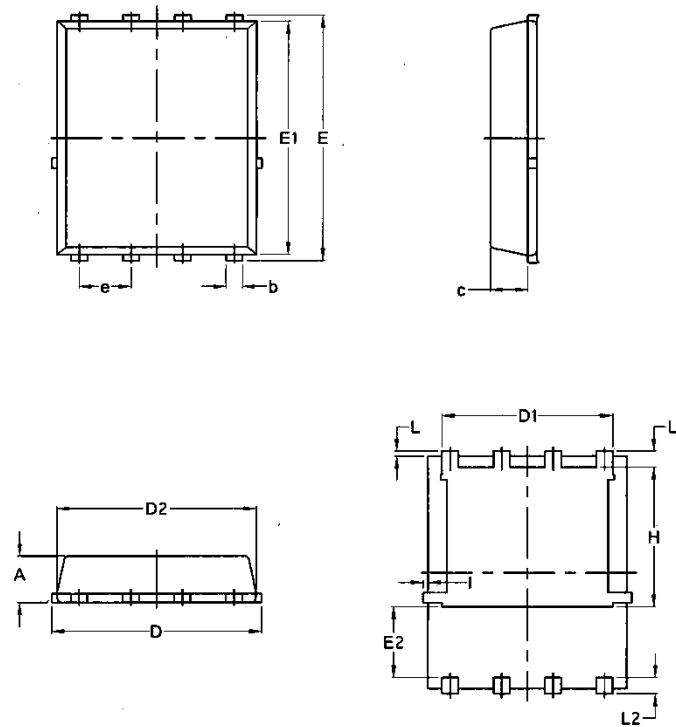


Fig.11 Unclamped Inductive Switching Waveform

## Package Mechanical Data-DFN5\*6-8-JQ Single



Symbol	Common			
	mm		Inch	
	Min	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070